

Di Jiang

List of Publications by Year in descending order

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Version: 2024-02-01

14
papers

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citations

1163117
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14
all docs

14
docs citations

14
times ranked

336
citing authors

#	ARTICLE	IF	CITATIONS
1	A flexible and stackable 3D interconnect system using growth-engineered carbon nanotube scaffolds. Flexible and Printed Electronics, 2017, 2, 025003.	2.7	6
2	Embedded Finâ€Like Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. Small, 2016, 12, 1521-1526.	10.0	15
3	Flexible Multifunctionalized Carbon Nanotubesâ€Based Hybrid Nanowires. Advanced Functional Materials, 2015, 25, 4135-4143.	14.9	20
4	Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. Journal of Electronic Materials, 2015, 44, 2898-2907.	2.2	21
5	Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. IEEE Electron Device Letters, 2015, 36, 499-501.	3.9	44
6	Reliability of carbon nanotube bumps for chip on glass application. , 2014, , .		2
7	Carbon nanotube/solder hybrid structure for interconnect applications. , 2014, , .		0
8	Chemically vapor deposited carbon nanotubes for vertical electronics interconnect in packaging applications. , 2014, , .		2
9	Carbon nanotubes for electronics manufacturing and packaging: from growth to integration. Advances in Manufacturing, 2013, 1, 13-27.	6.1	22
10	Effect of substrates and underlayer on CNT synthesis by plasma enhanced CVD. Advances in Manufacturing, 2013, 1, 236-240.	6.1	2
11	Paper-mediated controlled densification and low temperature transfer of carbon nanotube forests for electronic interconnect application. Microelectronic Engineering, 2013, 103, 177-180.	2.4	30
12	Reliability of carbon nanotube bumps for chip on film application. , 2013, , .		0
13	Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. IEEE Electron Device Letters, 2012, 33, 420-422.	3.9	67
14	Formation of three-dimensional carbon nanotube structures by controllable vapor densification. Materials Letters, 2012, 78, 184-187.	2.6	17